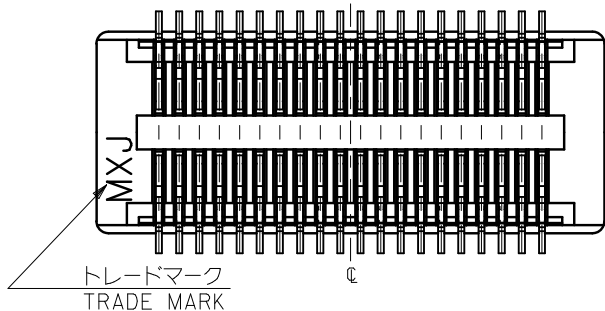


30極以下品形状  
SHAPE OF 30 CIRCUITS OR LESS



注記 NOTES:

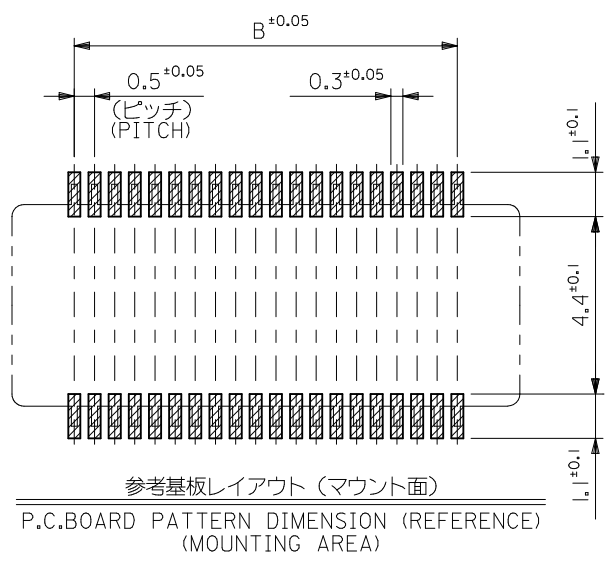
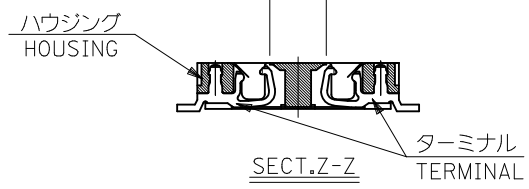
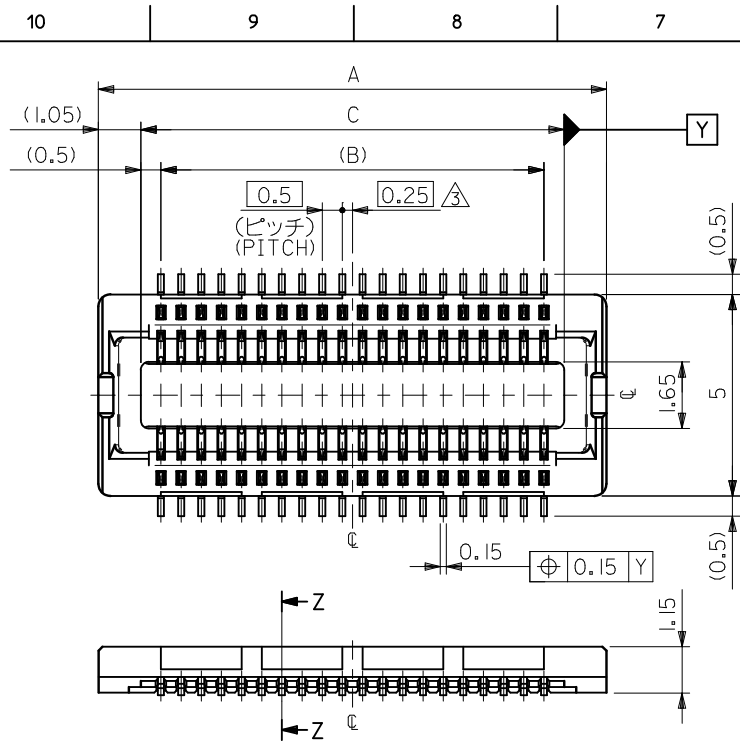
1. 使用材料 MATERIAL  
ハウジング: 液晶ポリマー ガラス充填、UL94V-0 (黒)  
HOUSING: LIQUID CRYSTAL POLYMER (GLASS FILLED)  
UL94V-0, (COLOR: BLACK)  
ターミナル: リン青銅 (t=0.15)  
TERMINAL: PHOSPHOR BRONZE (t=0.15)
2. メッキ仕様 PLATING  
金メッキ 0.25マイクロメートル以上 (コンタクト部)  
GOLD 0.25 MICROMETER MINIMUM (CONTACT AREA)  
金メッキ 0.4マイクロメートル以下 (テール部)  
GOLD 0.4 MICROMETER MAXIMUM (TAIL AREA)  
下地メッキ: ニッケルメッキ 1.5マイクロメートル以上  
UNDER PLATING: NICKEL 1.5 MICROMETER MINIMUM  
\*コンタクト部とテール部はニッケルメッキによって  
分断されている金メッキです。  
DIVIDE INTO PARTS THE GOLD PLATING OF THE CONTACT  
AND THE TAIL PART BY THE NICKEL PLATING.

- ③ (全極数/2) = 偶数の場合に適用。  
APPLY FOR (CIRCUIT/2) = EVEN.
4. 嵌合相手: 55560シリーズ, 53794シリーズ  
MATE WITH: 55560 SERIES, 53794 SERIES.
  5. テール平坦度は、0.1以下  
TAIL COPLANARITY TO BE 0.1 MAXIMUM.

8.0	7.0	10.1	54722-0304	54722-0303	30
6.5	5.5	8.6	54722-0244	54722-0243	24
6.0	5.0	8.1	54722-0224	54722-0223	22
5.5	4.5	7.6	54722-0204	54722-0203	20
4.5	3.5	6.6	54722-0164	54722-0163	16
C	B	A	EMBSTP PKG. ORDER No. オーダー番号	MATERIAL No.	極数 CIRCUIT

MODEL No. 54722-\*\*\*3

REVISED EC NO: J2010-1489 DRWN: TOSHIMA CHKD: SMARUYAMA APPR: MSASAO	DESCRIPTION 2010/02/01 2010/02/02 2010/02/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY T. ITO	DATE '03/08/20	TITLE 0.5 B-T-O-B CONN REC ASSY [NI BARRIER] (HGT=15) -LEAD FREE-			
		10 OVER 30 UNDER	±0.25	CHECKED BY T. YAMAGUCHI	DATE '03/08/20	MOLEX INCORPORATED			
		30 OVER	±0.3	APPROVED BY T. YAMAGUCHI	DATE '03/08/20	DOCUMENT NO. SD-54722-011			
		ANGULAR	±3 °	MATERIAL NO. SEE CHART		SHEET NO. 1 OF 2			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

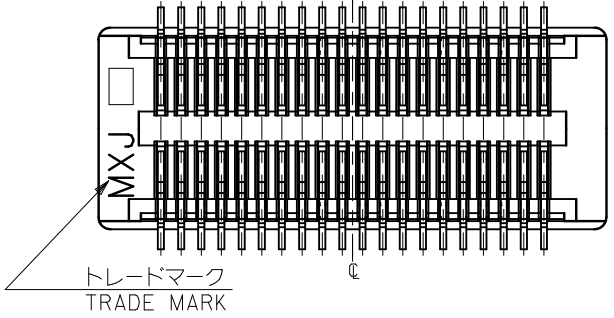


34極以上品形状  
SHAPE OF 34CIRCUITS OR MORE

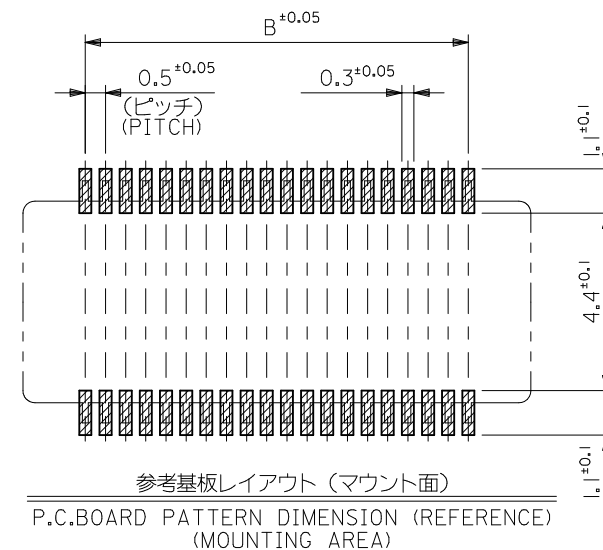
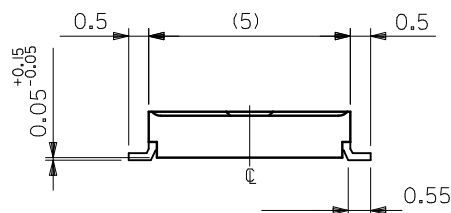
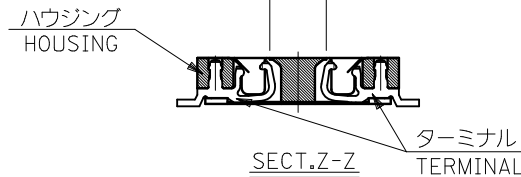
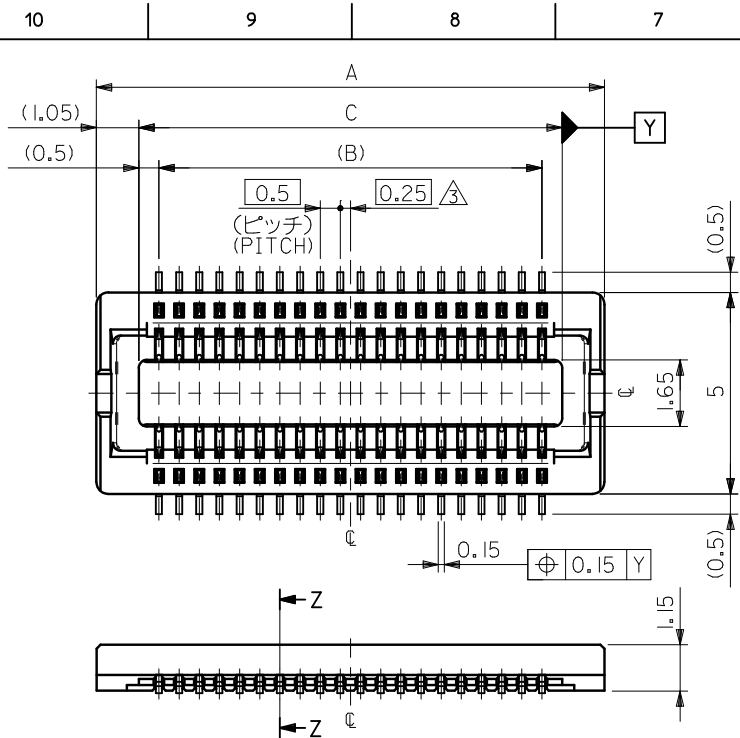
- 注記 NOTES:
- 使用材料 MATERIAL  
 ハウジング: 液晶ポリマー ガラス充填, UL94V-0 (黒)  
 HOUSING: LIQUID CRYSTAL POLYMER (GLASS FILLED)  
 UL94V-0, (COLOR:BLACK)  
 ターミナル: リン青銅 (t=0.15)  
 TERMINAL: PHOSPHOR BRONZE (t=0.15)
  - メッキ仕様 PLATING  
 金メッキ 0.25マイクロメートル以上 (コンタクト部)  
 GOLD 0.25 MICROMETER MINIMUM (CONTACT AREA)  
 金メッキ 0.4マイクロメートル以下 (テール部)  
 GOLD 0.4 MICROMETER MAXIMUM (TAIL AREA)  
 下地メッキ: ニッケルメッキ 1.5マイクロメートル以上  
 UNDER PLATING: NICKEL 1.5 MICROMETER MINIMUM  
 \*コンタクト部とテール部はニッケルメッキによって  
 分断されている金メッキです。  
 DIVIDE INTO PARTS THE GOLD PLATING OF THE CONTACT  
 AND THE TAIL PART BY THE NICKEL PLATING.

- △ (全極数/2) = 偶数の場合に適用。  
 APPLY FOR (CIRCUIT/2)=EVEN.
- 嵌合相手: 55560シリーズ, 53794シリーズ  
 MATE WITH: 55560 SERIES, 53794 SERIES.
  - テール平坦度は、0.1以下  
 TAIL COPLANARITY TO BE 0.1 MAXIMUM.

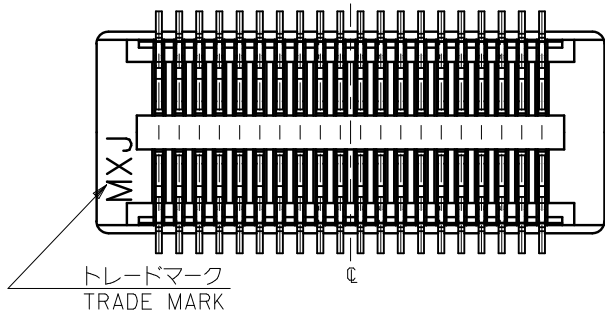
20.5	19.5	22.6	54722-0804	54722-0803	80
15.5	14.5	17.6	54722-0604	54722-0603	60
13.0	12.0	15.1	54722-0504	54722-0503	50
10.5	9.5	12.6	54722-0404	54722-0403	40
9.0	8.0	11.1	54722-0344	54722-0343	34
C	B	A	EMBSTP PKG. ORDER No. オーダー番号	MATERIAL No.	極数 CIRCUIT



REVISED EC NO: J2010-1489 DRWN: TOSHIMA CHKD: SMARUYAMA APPR: MSASAO	DESCRIPTION 2010/02/01 2010/02/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	MODEL No. 54722-***3	
		10 UNDER	±0.2	DRAWN BY T. ITO	DATE '03/08/20	TITLE 0.5 B-TO-B CONN REC ASSY [NI BARRIER] (HGT=15) -LEAD FREE-			
		10 OVER 30 UNDER	±0.25	CHECKED BY T. YAMAGUCHI	DATE '03/08/20	MATERIAL NO. SEE CHART			
		30 OVER	±0.3	APPROVED BY T. YAMAGUCHI	DATE '03/08/20	DOCUMENT NO. SD-54722-011			
REV	SIZE A3	ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



30極以下品形状  
SHAPE OF 30 CIRCUITS OR LESS



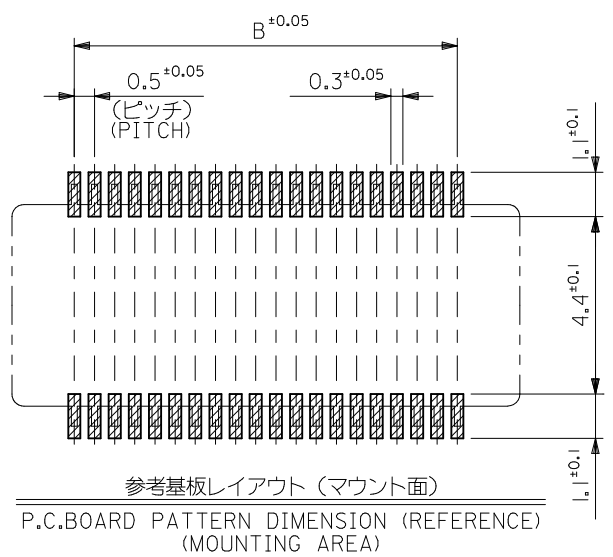
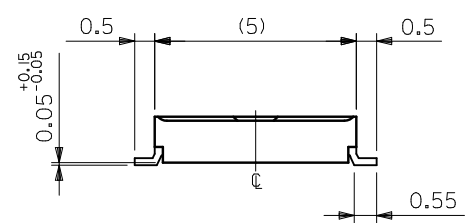
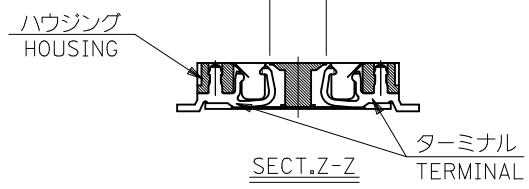
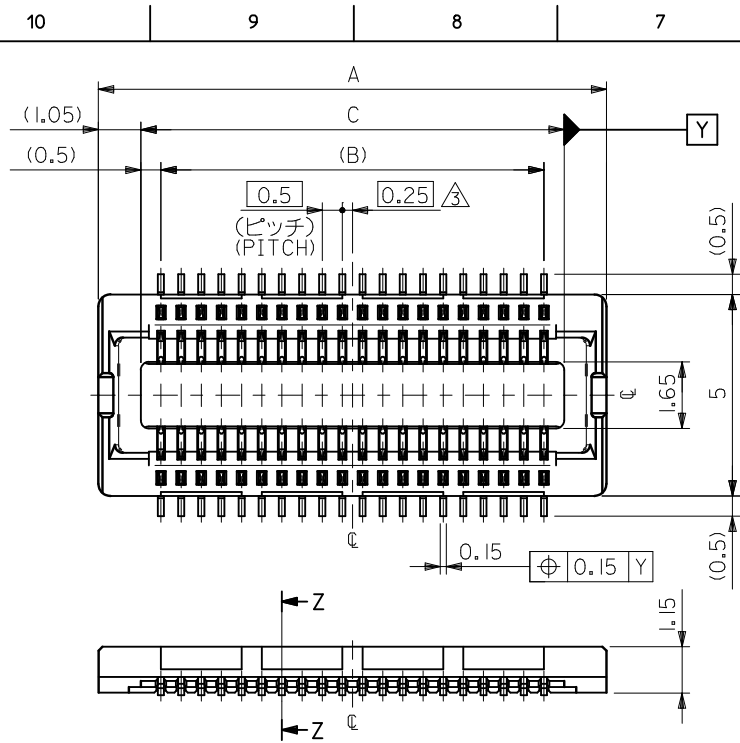
注記 NOTES:

1. 使用材料 MATERIAL  
ハウジング: 液晶ポリマー ガラス充填、UL94V-0 (黒)  
HOUSING: LIQUID CRYSTAL POLYMER (GLASS FILLED)  
UL94V-0, (COLOR: BLACK)  
ターミナル: リン青銅 (t=0.15)  
TERMINAL: PHOSPHOR BRONZE (t=0.15)
2. メッキ仕様 PLATING  
金メッキ 0.25マイクロメートル以上 (コンタクト部)  
GOLD 0.25 MICROMETER MINIMUM (CONTACT AREA)  
金メッキ 0.4マイクロメートル以下 (テール部)  
GOLD 0.4 MICROMETER MAXIMUM (TAIL AREA)  
下地メッキ: ニッケルメッキ 1.5マイクロメートル以上  
UNDER PLATING: NICKEL 1.5 MICROMETER MINIMUM  
\*コンタクト部とテール部はニッケルメッキによって  
分断されている金メッキです。  
DIVIDE INTO PARTS THE GOLD PLATING OF THE CONTACT  
AND THE TAIL PART BY THE NICKEL PLATING.

3. (全極数/2) = 偶数の場合に適用。  
APPLY FOR (CIRCUIT/2)=EVEN.
4. 嵌合相手: 55560シリーズ, 53794シリーズ  
MATE WITH: 55560 SERIES, 53794 SERIES.
5. テール平坦度は、0.1以下  
TAIL COPLANARITY TO BE 0.1 MAXIMUM.

8.0	7.0	10.1	54722-0304	54722-0303	30
6.5	5.5	8.6	54722-0244	54722-0243	24
6.0	5.0	8.1	54722-0224	54722-0223	22
5.5	4.5	7.6	54722-0204	54722-0203	20
4.5	3.5	6.6	54722-0164	54722-0163	16
C	B	A	EMBSTP PKG. ORDER No. オーダー番号	MATERIAL No.	極数 CIRCUIT

REVISED EC NO: J2010-1489 DRWN: TOSHIMA CHKD: SMARUYAMA APPR: MSASAO	DESCRIPTION 2010/02/01 2010/02/02 2010/02/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	MODEL No. 54722-***3	
		10 UNDER	±0.2	DRAWN BY T. ITO	DATE '03/08/20	TITLE 0.5 B-T-O-B CONN REC ASSY [NI BARRIER] (HGT=15) -LEAD FREE-			
		10 OVER 30 UNDER	±0.25	CHECKED BY T. YAMAGUCHI	DATE '03/08/20	MOLEX INCORPORATED			
		30 OVER	±0.3	APPROVED BY T. YAMAGUCHI	DATE '03/08/20				
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-54722-011		SHEET NO. 1 OF 2	

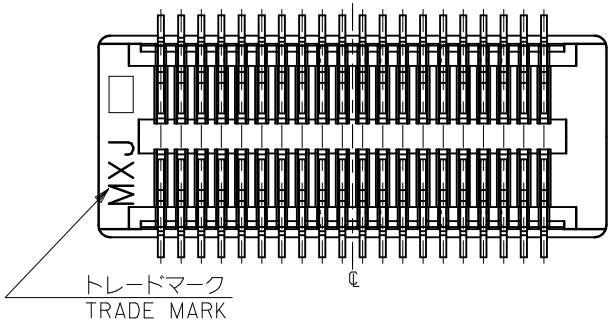


34極以上品形状  
SHAPE OF 34CIRCUITS OR MORE

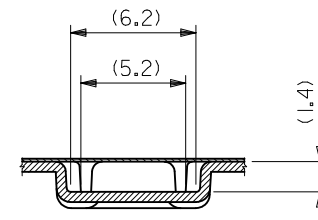
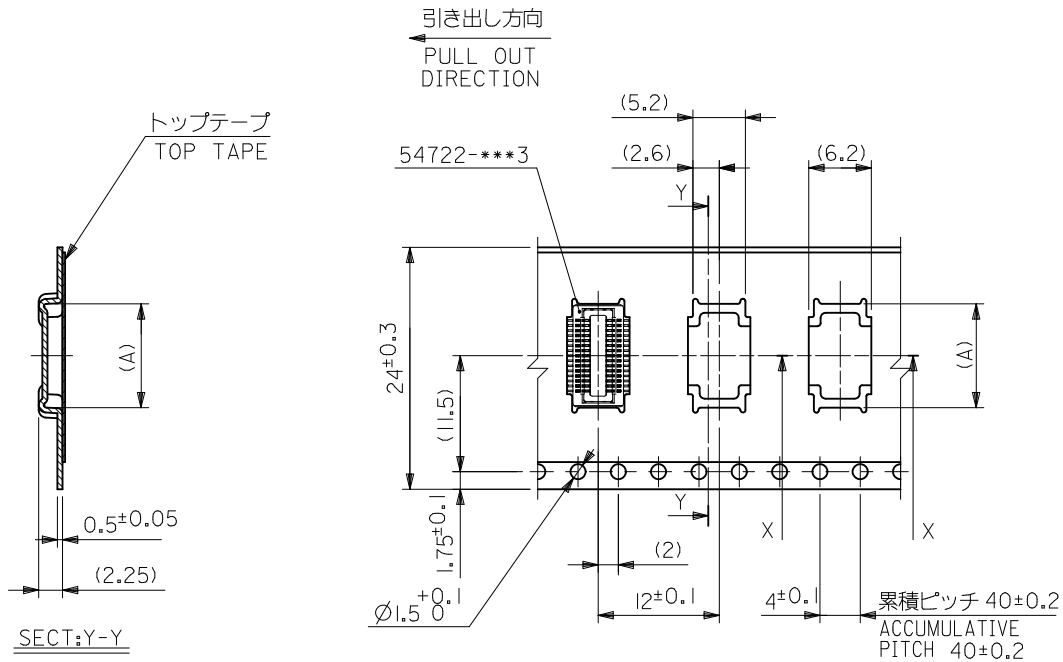
- 注記 NOTES:
- 使用材料 MATERIAL  
 ハウジング: 液晶ポリマー ガラス充填, UL94V-0 (黒)  
 HOUSING: LIQUID CRYSTAL POLYMER (GLASS FILLED)  
 UL94V-0, (COLOR:BLACK)  
 ターミナル: リン青銅 (t=0.15)  
 TERMINAL: PHOSPHOR BRONZE (t=0.15)
  - メッキ仕様 PLATING  
 金メッキ 0.25マイクロメートル以上 (コンタクト部)  
 GOLD 0.25 MICROMETER MINIMUM (CONTACT AREA)  
 金メッキ 0.4マイクロメートル以下 (テール部)  
 GOLD 0.4 MICROMETER MAXIMUM (TAIL AREA)  
 下地メッキ: ニッケルメッキ 1.5マイクロメートル以上  
 UNDER PLATING: NICKEL 1.5 MICROMETER MINIMUM  
 \*コンタクト部とテール部はニッケルメッキによって  
 分断されている金メッキです。  
 DIVIDE INTO PARTS THE GOLD PLATING OF THE CONTACT  
 AND THE TAIL PART BY THE NICKEL PLATING.

- △3 (全極数/2) = 偶数の場合に適用。  
 APPLY FOR (CIRCUIT/2)=EVEN.
- 嵌合相手: 55560シリーズ, 53794シリーズ  
 MATE WITH: 55560 SERIES, 53794 SERIES.
  - テール平坦度は、0.1以下  
 TAIL COPLANARITY TO BE 0.1 MAXIMUM.

20.5	19.5	22.6	54722-0804	54722-0803	80
15.5	14.5	17.6	54722-0604	54722-0603	60
13.0	12.0	15.1	54722-0504	54722-0503	50
10.5	9.5	12.6	54722-0404	54722-0403	40
9.0	8.0	11.1	54722-0344	54722-0343	34
C	B	A	EMBSTP PKG. ORDER No. オーダー番号	MATERIAL No.	極数 CIRCUIT



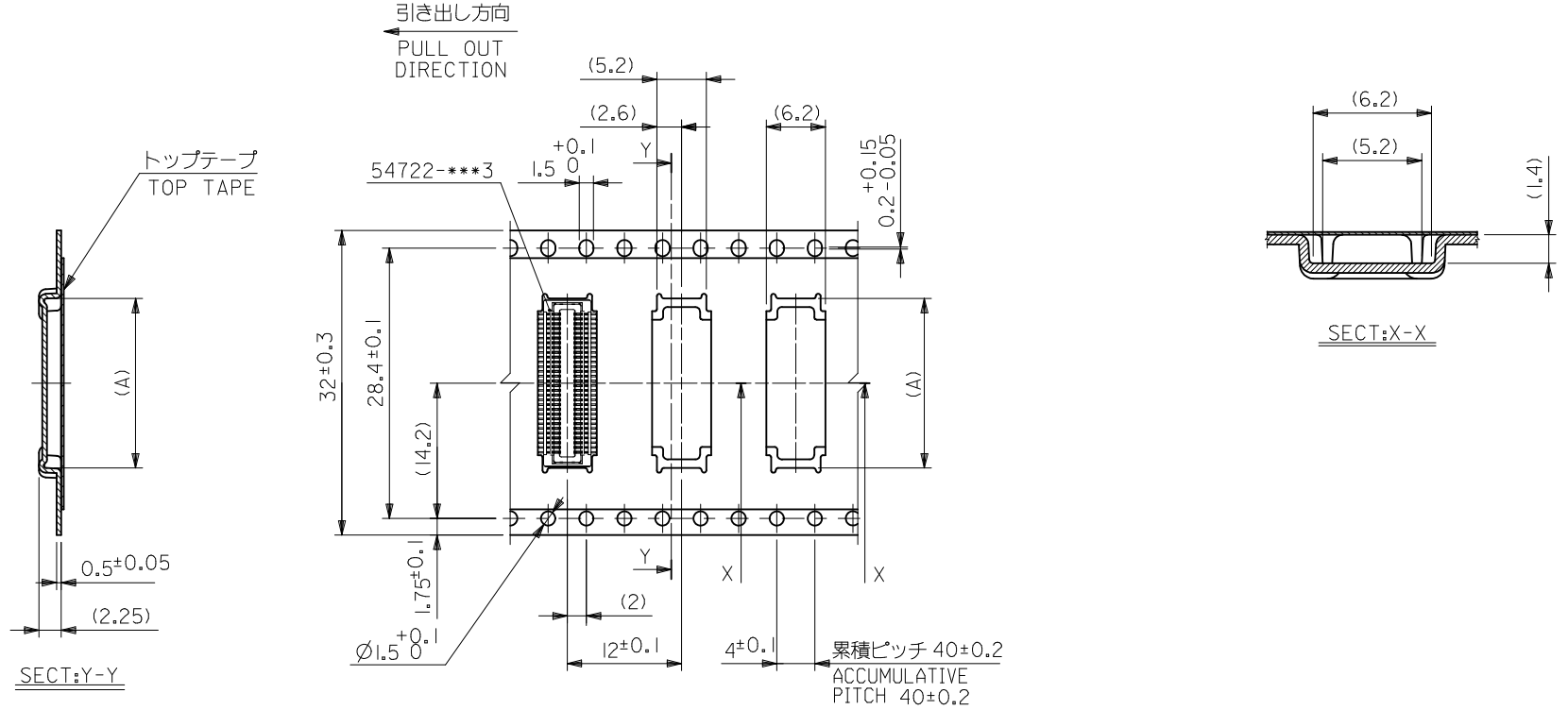
REVISED EC NO: J2010-1489 DRWN: TOSHIMA CHKD: SMARUYAMA APPR: MSASAO	DESCRIPTION 2010/02/01 2010/02/02 2010/02/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	MODEL No. 54722-***3	
		10 UNDER	±0.2	DRAWN BY T. ITO	DATE '03/08/20	TITLE 0.5 B-TO-B CONN REC ASSY [NI BARRIER] (HGT=15) -LEAD FREE-			
		10 OVER 30 UNDER	±0.25	CHECKED BY T. YAMAGUCHI	DATE '03/08/20	MATERIAL NO. SEE CHART			
		30 OVER	±0.3	APPROVED BY T. YAMAGUCHI	DATE '03/08/20	DOCUMENT NO. SD-54722-011			
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		SHEET NO. 2 OF 2			



24mm幅キャリアテープ  
24mm WIDTH CARRIER TAPE

24	29.4	25.4	15.3	54722-0504	50
			12.8	54722-0404	40
			11.3	54722-0344	34
			10.3	54722-0304	30
			8.8	54722-0244	24
			8.3	54722-0224	22
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	(A)	MATERIAL NO.	極数 CIRCUIT

REVISED EC NO: J2010-1489 DRWN: TOSHIMA 2010/02/01 CHKD: SMARUYAMA 2010/02/02 APPR: MSASAO 2010/02/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	MODEL NO. 54722-***4
	10 UNDER	±0.2	DRAWN BY T. ITO	DATE '03/08/20	TITLE 0.5 B-TO-B CONN REC ASSY [NI BARRIER] EMBSTP PKG -LEAD FREE-	
	10 OVER 30 UNDER	±0.25	CHECKED BY T. YAMAGUCHI	DATE '03/08/20	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY T. YAMAGUCHI	DATE '03/08/20	DOCUMENT NO. SD-54722-012	SHEET NO. 3 OF 5
	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



32mm幅キャリアテープ  
32mm WIDTH CARRIER TAPE

32	37.4	33.4	17.8	54722-0604	60
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	(A)	MATERIAL NO.	極数 CIRCUIT

REVISED EC NO: J2010-1489 DRWN: TOSHIMA CHKD: SMARUYAMA APPR: MSASAO	DESCRIPTION 2010/02/01 2010/02/02 2010/02/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	MODEL NO. 54722-***4	
		10 UNDER	±0.2	DRAWN BY T. ITO	DATE '03/08/20	TITLE 0.5 B-TO-B CONN REC ASSY [NI BARRIER] EMBSTP PKG -LEAD FREE-		
		10 OVER 30 UNDER	±0.25	CHECKED BY T. YAMAGUCHI	DATE '03/08/20	MOLEX INCORPORATED		
		30 OVER	±0.3	APPROVED BY T. YAMAGUCHI	DATE '03/08/20	DOCUMENT NO. SD-54722-012		
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART		SHEET NO. 4 OF 5		
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				